



DEFENSE LOGISTICS AGENCY
LAND AND MARITIME
POST OFFICE BOX 3990
COLUMBUS, OH 43218-3990

September 16, 2019

Nancy Shindler
Director of Quality
Teledyne e2v Inc.
765 Sycamore Drive
Milpitas, CA 95035 USA

Dear Ms. Shindler:

Re: Laboratory Suitability for MIL-STD-883; FSC 5962; VQ (VQC-19-034317); Tran CN: 052934

Teledyne e2v HiRel Electronics has demonstrated to the DLA Land and Maritime compliance with MIL-STD-883, the test standard for integrated circuits. Teledyne e2v Inc. is granted laboratory suitability, effective on the date of this letter, for the facilities, test methods and conditions shown on the enclosure. All testing must be performed in accordance with MIL-PRF-38535 and MIL-STD-883 test methods.

This letter is issued in conjunction with the QML certification letter DLA Land and Maritime- VQ (VQC-19-034316). This Laboratory Suitability is subject to the policies, procedures, and conditions of the Defense Standardization Program, as published in the manual DoD 4120.24-M and SD-6.

This laboratory suitability is valid until terminated by written notice from DLA Land and Maritime. If warranted, it may be withdrawn by DLA Land and Maritime at any time. Each of these facilities is subject to an audit by DLA Land and Maritime with a minimum notice.

If you have any questions, please contact Mr. Tran (614) 692-0606.

Sincerely,

Robert M. Heber
Chief
Sourcing and Qualification Division

Enclosure

Enclosure to DLA Land and Maritime- (VQC-19-034317)

Test	883 Test Method / Condition	Location	Additional Location
Insulation Resistance	1003	Teledyne e2v HiRel Electronics	
Moisture Resistance	1004	Teledyne e2v HiRel Electronics	
Steady State Life Test	1005 A, B, C, D	Teledyne e2v HiRel Electronics	Liberty Labs
Stabilization Bake	1008 A, B, C	Teledyne e2v HiRel Electronics	
Salt Atmosphere	1009 A, B	Teledyne e2v HiRel Electronics	
Temperature Cycling	1010 B, C	Teledyne e2v HiRel Electronics	Microchip Technologies
Thermal Shock	1011 B, C	Teledyne e2v HiRel Electronics	
Seal	1014 A1, A2, A4, C1	Teledyne e2v HiRel Electronics	Microchip Technologies
Burn-in	1015 A, B, C, D	Teledyne e2v HiRel Electronics	Liberty Labs
Internal Gas Analysis	1018	Seal Labs	Atlantic Analytical
Constant Acceleration	2001 A, B, D, E (Y1 orientation only)	Teledyne e2v HiRel Electronics	Microchip Technologies
Mechanical Shock	2002 B	Teledyne e2v HiRel Electronics	
Solderability	2003	Teledyne e2v HiRel Electronics	
Lead Integrity	2004 B1, B2, D	Teledyne e2v HiRel Electronics	
Vibration, Variable Frequency	2007 A	Teledyne e2v HiRel Electronics	
External Visual	2009	Teledyne e2v HiRel Electronics	Microchip Technologies
Internal Visual	2010 A, B	Teledyne e2v HiRel Electronics	Microchip Technologies
Bond Strength	2011 D	Teledyne e2v HiRel Electronics	Microchip Technologies
Radiography	2012	NDT	
Internal Visual for DPA	2013	Teledyne e2v HiRel Electronics	
Internal Visual & Mechanical	2014	Teledyne e2v HiRel Electronics	
Resistance to Solvents	2015	Teledyne e2v HiRel Electronics	
Physical Dimensions	2016	Teledyne e2v HiRel Electronics	
Internal Visual (Hybrids)	2017	Teledyne e2v HiRel Electronics	
SEM	2018	Analytical Solutions	
Die Shear Strength	2019	Teledyne e2v HiRel Electronics	Microchip Technologies
PIND	2020 A, B	Teledyne e2v HiRel Electronics	
Glassivation Layer Integrity	2021	Teledyne e2v HiRel Electronics	Analytical Solutions
Nondestructive Bond Pull	2023	Teledyne e2v HiRel Electronics	
Lid Torque	2024	Teledyne e2v HiRel Electronics	
Adhesion of Lead Finish	2025	Teledyne e2v HiRel Electronics	
Substrate Attach Strength	2027	Teledyne e2v HiRel Electronics	Microchip Technologies
Pin-Grid Package Destructive Lead Pull Test	2028	Teledyne e2v HiRel Electronics	
Visual Inspection of Passive Elements	2032	Teledyne e2v HiRel Electronics	
Resistance to Soldering Heat	2036 B	Teledyne e2v HiRel Electronics	
ESDS Classification	3015	ICE, Inc.	
Wafer Lot Acceptance	5007	Analytical Solutions	
Electrical Test	Per Mil-STD-883 paragraph 4.5	Teledyne e2v HiRel Electronics	Integra
Internal Visual Transistors (Pre-cap) Inspection	2072 of Mil-Std-750	Teledyne e2v HiRel Electronics	

Subcontractors:

Analytical Solutions, Inc.
Atlantic Analytical
Corwil Technology Corp.
Golden Altos
HGM
ICE, Inc.
Integra
Liberty labs
Microchip Technologies
NDT
Seal Labs
Six Sigma
Team Pacific

Locations:

Albuquerque, NM, USA
Whitehouse, NJ, USA
Milpitas, CA, USA
Milpitas, CA, USA
Santa Clara, CA, USA
San Jose, CA, USA
Wichita, KS, USA
Milpitas, CA, USA
Bangkok, Thailand
Sunnyvale, CA, USA
El Segundo, CA, USA
Milpitas, CA, USA
Taguig City, Phillipians